■Bus Cycle Time

• 83.3ns (When CF=12MHz)

Note: The bus cycle time here refers to the ROM read speed.

- ■Minimum Instruction Cycle Time (tCYC)
 - 250ns (When CF=12MHz)

■Ports

• I/O ports

Ports whose I/O direction can be designated in 1-bit units	28 (P10 to P17, P20 to P27, P30 to P34,
	P70 to P73, PWM0, PWM1, XT2)
Ports whose I/O direction can be designated in 4-bit units	8 (P00 to P07)
• USB ports	2 (UHD+, UHD-)
 Dedicated oscillator ports 	2 (CF1, CF2)
• Input-only port (also used for oscillation)	1 (XT1)
• Reset pins	$1 (\overline{\text{RES}})$
• Power supply pins	6 (VSS1 to 3, VDD1 to 3)

- ■Timers
 - Timer 0: 16-bit timer/counter with 2 capture registers.
 - Mode 0: 8-bit timer with an 8-bit programmable prescaler (with two 8-bit capture registers) \times 2 channels Mode 1: 8-bit timer with an 8-bit programmable prescaler (with two 8-bit capture registers)
 - + 8-bit counter (with two 8-bit capture registers)
 - Mode 2: 16-bit timer with an 8-bit programmable prescaler (with two 16-bit capture registers)
 - Mode 3: 16-bit counter (with two 16-bit capture registers)
 - Timer 1: 16-bit timer/counter that supports PWM/toggle outputs
 - Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs) + 8-bit timer/
 - counter with an 8-bit prescaler (with toggle outputs)
 - Mode 1: 8-bit PWM with an 8-bit prescaler \times 2 channels
 - Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs)
 - (toggle outputs also possible from lower-order 8 bits)
 - Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs)
 - (lower-order 8 bits may be used as a PWM output)
 - Timer 4: 8-bit timer with a 6-bit prescaler
 - Timer 5: 8-bit timer with a 6-bit prescaler
 - Timer 6: 8-bit timer with a 6-bit prescaler (with toggle outputs)
 - Timer 7: 8-bit timer with a 6-bit prescaler (with toggle outputs)
 - Base timer
 - 1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.
 - 2) Interrupts programmable in 5 different time schemes

■SIO

- SIO0: Synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Transfer clock cycle: 4/3 to 512/3 tCYC
 - Automatic continuous data transmission (1 to 256 bits, specifiable in 1-bit units) (Suspension and resumption of data transmission possible in 1 byte units)
- SIO1: 8-bit asynchronous/synchronous serial interface
 - Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks) Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)
 - Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)
 - Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)
- SIO4: Synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Transfer clock cycle: 4/3 to 1020/3 tCYC
 - Automatic continuous data transmission (1 to 4096 bytes, specifiable in 1 byte units) (Suspension and resumption of data transmission possible in 1 byte units or in word units)
 - 4) Auto-start-on-falling-edge function
 - 5) Clock polarity selectable
 - 6) CRC16 calculator circuit built in

- SIO9: Synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Transfer clock cycle: 4/3 to 1020/3 tCYC
 - Automatic continuous data transmission (1 to 4096 bytes, specifiable in 1 byte units) (Suspension and resumption of data transmission possible in 1 byte units or word units)
 - 4) Auto-start-on-falling-edge function
 - 5) Clock polarity selectable
 - 6) CRC16 calculator circuit built in

■Full Duplex UART

- 1) Data length: 7/8/9 bits selectable
- 2) Stop bits: 1 bit (2 bits in continuous transmission mode)
- 3) Baud rate: 16/3 to 8192/3 tCYC
- ■AD Converter: 8 bits × 12 channels
- ■PWM: Multifrequency 12-bit PWM × 2 channels

■Infrared Remote Control Receiver Circuit

- 1) Noise rejection function (noise filter time constant: Approx. 120µs when the 32.768kHz crystal oscillator is selected as the base clock)
- 2) Supports data encoding systems such as PPM (Pulse Position Modulation) and Manchester encoding.
- 3) X'tal HOLD mode reset function

■USB Interface (host control function)

- 1) Compliant with full-speed (12M bps) specifications
- 2) Supports 4 transfer types (control transfer, bulk transfer, interrupt transfer, and isochronous transfer).

■Audio Interface

- 1) Sampling frequency (fs):32kHz, 44.1kHz, 48kHz
- 2) Master clock frequency (internal PLL): 12.288MHz, 16.9344MHz, 18.432MHz
- 3) Bit clock selectable: 48fs/64fs
- 4) Data bit length: 16/18/20/24 bits
- 5) LSB first/MSB firsts selectable
- 6) Left-justification/right-justification selectable
- ■Watchdog Timer
 - Watchdog timer using external RC circuitry
 - Interrupt and reset signals selectable

■Clock Output Function

- 1) Can output a clock with a clock rate of 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, or 1/64 of the source oscillator clock selected as the system clock.
- 2) Can output the source oscillation clock for the subclock.

■Interrupts

• 40 sources, 10 vector addresses

- 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
- 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4/UHC bus active/remote control signal receive
4	0001BH	H or L	INT3/INT5/base timer
5	00023H	H or L	T0H/INT6/UHC device connected/UHC disconnected/UHC resume
6	0002BH	H or L	T1L/T1H/INT7/SIO9/AIF start
7	00033H	H or L	SIO0/UART1 receive
8	0003BH	H or L	SIO1/SIO4/UART1 transmit/end of AIF
9	00043H	H or L	ADC/T6/T7/UHC-ACK/UHC-NAK/UHC error/UHC STALL
10	0004BH	H or L	Port 0/PWM0/PWM1/T4/T5/UHC-SOF/DMCOPY

• Priority levels X > H > L

• Of interrupts of the same level, the one with the smallest vector address takes precedence.

Subroutine Stack Levels: 8192 levels maximum (The stack is allocated in RAM.)

■High-speed Multiplication/Division Instructions

- 16 bits \times 8 bits (5 tCYC execution time)
- 24 bits \times 16 bits (12 tCYC execution time)
- 16 bits ÷ 8 bits (8 tCYC execution time)
- 24 bits ÷ 16 bits (12 tCYC execution time)

Oscillation and PLL Circuits

- RC oscillation circuit (internal): For system clock
- CF oscillation circuit: For system clock
- Crystal oscillation circuit: For system clock, time-of-day clock
- PLL circuit (internal): For USB interface (see Fig.5)), audio interface (see Fig. 6)

■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
 - 1) Oscillation is not halted automatically.
 - 2) Canceled by a system reset or occurrence of an interrupt.
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
- 1) The PLL base clock generator, CF, RC and crystal oscillators automatically stop operation.
- 2) There are four ways of resetting the HOLD mode.
- (1) Setting the reset pin to the lower level.
- (2) Setting at least one of the INTO, INT1, INT2, INT4, and INT5 pins to the specified level
- (3) Having an interrupt source established at port 0
- (4) Having an bus active interrupt source established in the USB host controll circuit
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer.
 - 1) The PLL base clock generator, CF and RC oscillator automatically stop operation.
 - 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
 - 3) There are six ways of resetting the X'tal HOLD mode.
 - (1) Setting the reset pin to the low level
 - (2) Setting at least one of the INTO, INT1, INT2, INT4, and INT5 pins to the specified level
 - (3) Having an interrupt source established at port 0
 - (4) Having an interrupt source established in the base timer circuit
 - (5) Having an bus active interrupt source established in the USB host controll circuit
 - (6) Having an interrupt source established in the infrared remote controller receiver circuit

■Development Tools

• On-chip debugger: TCB87- type-B + LC87F1HC8A

■Flash ROM Programming Boards

Package	Programming boards
SQFP48(7×7)	W87F55256SQ

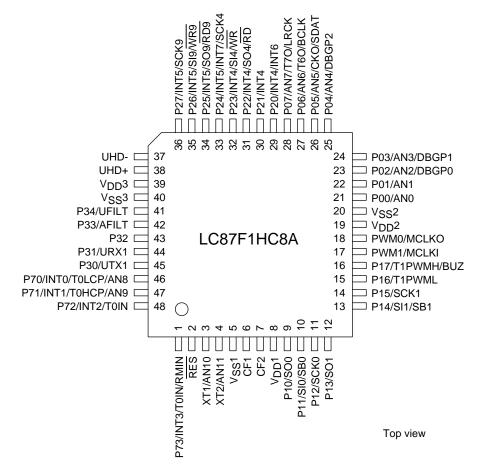
■Recommended EPROM Programmer

Maker		Model	Supported version	Device
Flash Support Group, Inc. (FSG)	Single Programmer	AF9708/ AF9709/AF9709B/AF9709C (Including Ando Electric Co., Ltd. models)	Rev 02.82 or later	LC87F1HC8A
Flash Support Group, Inc. (FSG) + Our company(Note 1)	Onboard Single/Gang Programmer	AF9101/AF9103(Main body) (FSG models) SIB87(Inter Face Driver) (Our company model)	(Note 2)	LC87F1HC8A
	Single/Gang Programmer	SKK/SKK TypeB (SANYO FWS)	Application Version 2.04 or later	1007541100
Our company	Onboard Single/Gang Programmer	SKK-DBG TypeB (SANYO FWS)	Chip Data Version 2.11 or later	LC87F1HC8

Note 1: With the FSG onboard programmer (AF9101/AF9103) and the serial interface driver (SIB87) provided by Our company, PC-less standalone onboard programming is possible

Note 2: Depending on programming conditions, it is necessary to use a dedicated programming device and a program. Please contact Our company or FSG if you have any questions or difficulties regarding this matter.

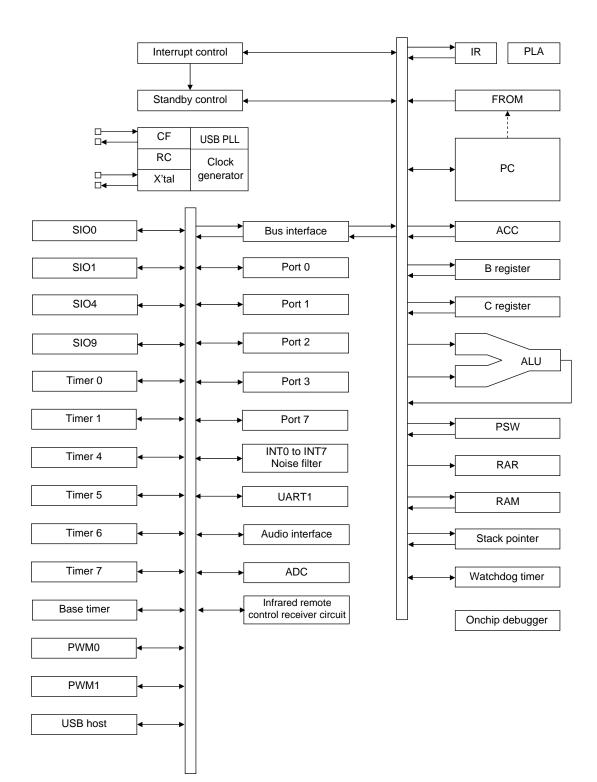
Pin Assignment



SQFP48(7×7) "Lead-/Halogen-free Type"

SQFP48	NAME	SQFP48	NAME
1	P73/INT3/T0IN/RMIN	25	P04/AN4/DBGP2
2	RES	26	P05/AN5/CKO/SDAT
3	XT1/AN10	27	P06/AN6/T6O/BCLK
4	XT2/AN11	28	P07/AN7/T7O/LRCK
5	V _{SS} 1	29	P20/INT4/INT6
6	CF1	30	P21/INT4
7	CF2	31	P22/INT4/SO4/RD
8	V _{DD} 1	32	P23/INT4/SI4/WR
9	P10/SO0	33	P24/INT5/INT7/SCK4
10	P11/SI0/SB0	34	P25/INT5/SO9/RD9
11	P12/SCK0	35	P26/INT5/SI9/WR9
12	P13/SO1	36	P27/INT5/SCK9
13	P14/SI1/SB1	37	UHD-
14	P15/SCK1	38	UHD+
15	P16/T1PWML	39	V _{DD} 3
16	P17/T1PWMH/BUZ	40	V _{SS} 3
17	PWM1/MCLKI	41	P34/UFILT
18	PWM0/MCLKO	42	P33/AFILT
19	V _{DD} 2	43	P32
20	V _{SS} 2	44	P31/URX1
21	P00/AN0	45	P30/UTX1
22	P01/AN1	46	P70/INT0/T0LCP/AN8
23	P02/AN2/DBGP0	47	P71/INT1/T0HCP/AN9
24	P03/AN3/DBGP1	48	P72/INT2/T0IN

System Block Diagram



Pin Description

Pin Name	I/O			De	scription			Option	
V _{SS} 1,V _{SS} 2, V _{SS} 3	-	- power supply						No	
V _{DD} 1, V _{DD} 2	-	+ power supply	1					No	
V _{DD} 3	-	USB reference	voltage					Yes	
Port 0	I/O	8-bit I/O ports	6					Yes	
P00 to P07		 I/O specifiabl 	e in 4-bit units						
		Pull-up resistors can be turned on and off in 4-bit units.							
		 HOLD reset i 							
		Port 0 interru	pt input						
		Pin functions							
			input ports: AN0		,				
			gger pins: DBGP clock output/aud						
			toggle output/aud		• •				
			toggle output/au						
Port 1	I/O	8-bit I/O ports			eremposedpor			Yes	
P10 to P17		 I/O specifiabl 							
11010117			ors can be turne	d on and off in 1	-bit units.				
		Pin functions							
		P10: SIO0 da	ta output	P14	4: SIO1 data inpu	ut/bus input/outp	ut		
		P11: SIO0 da	ta input/bus inpu	ut/output P1	5: SIO1 clock inp	ut/output			
	P12: SIO0 clock input/output P16: Timer 1 PWML output								
		P13: SIO1 da	ta output	P1	7: Timer 1 PWM	I output/beeper	output	Yes	
Port 2	I/O	• 8-bit I/O ports							
P20 to P27		-	• I/O specifiable in 1-bit units						
		Pull-up resistors can be turned on and off in 1-bit units.							
			• Pin functions						
		P20 to P23: INT4 input/HOLD reset input/timer 1 event input/timer 0L capture input/							
		timer 0H capture input P24 to P27: INT5 input/HOLD recet input/timer 1 event input/timer 0L capture input/							
		P24 to P27: INT5 input/HOLD reset input/timer 1 event input/timer 0L capture input/ timer 0H capture input							
		P20: INT6 input/timer 0L capture 1 input							
		P22: SIO4 data input/output/parallel interface \overline{RD} output							
		P23: SIO4 data input/output/parallel interface WR output							
		P24: SIO4 clock input/output/INT7 input/timer 0H capture 1 input							
		P25: SIO9 data input/output/parallel interface RD9 output							
		P26: SIO9 data input/output/parallel interface $\overline{WR9}$ output							
		P27: SIO9 clo	ock input/output						
		Interrupt ackr	owledge types	1		1	,		
			Rising	Falling	Rising & Falling	H level	L level		
		INT4	enable	enable	enable	disable	disable		
		INT5	enable	enable	enable	disable	disable		
		INT6	enable	enable	enable	disable	disable		
		INT7	enable	enable	enable	disable	disable		
Port 3	I/O	• 5-bit I/O ports	<u>,</u>					Yes	
P30 to P34								100	
		 I/O specifiable in 1-bit units Pull-up resistors can be turned on and off in 1-bit units. 							
		Pin functions							
		P30: UART1							
		P31: UART1	receive						
		P33: Audio in	terface PLL filter	r pin (see Fig. 6.)				
		P34: USB inte	erface PLL filter p	pin (see Fig. 5.)					

Continued on next page.

Pin Name	I/O		Description					
Port 7	I/O	• 4-bit I/O port						No
P70 to P73		• I/O specifiable i	n 1-bit units					
		Pull-up resistors can be turned on and off in 1-bit units.						
		Pin functions						
		P70: INT0 input	/HOLD reset inp	out/timer 0L cap	ture input/watch	dog timer output	t	
		P71: INT1 input	/HOLD reset inp	out/timer 0H cap	ture input			
		P72: INT2 input	/HOLD reset inp	out/timer 0 even	t input/timer 0L o	apture input/		
		high speed	l clock counter i	nput				
		P73: INT3 input	(input with nois	e filter)/timer 0	event input/timer	0H capture inp	ut/	
		IR remote	controller receiv	ver input				
		AD converter in	put ports: AN8(I	P70), AN9(P71)				
		Interrupt acknow	vledge types					
			Rising	Falling	Rising & Falling	H level	L level	
		INT0	enable	enable	disable	enable	enable	
		INT1	enable	enable	disable	enable	enable	
		INT2	enable	enable	enable	disable	disable	
		INT3	enable	enable	enable	disable	disable	
PWM0	I/O	PWM0, PWM1 or	utput port					No
PWM1		General-purpose	input port					
		Pin functions	Pin functions					
		PWM0: Audio interface master clock output PWM1: Audio interface master clock input						
UHD-	I/O	USB data I/O pin	UHD-/general-p	ourpose I/O port				No
UHD+	I/O	USB data I/O pin	UHD+/general-	purpose I/O por	t			No
RES	Input	Reset pin						No
XT1	Input	• 32.768kHz crys	tal oscillator inp	ut				No
		Pin functions						
		General-purpos	e input port					
		AD converter in	put ports: AN10					
		Must be connec	ted to V _{DD} 1 wh	nen not to be us	ed.			
XT2	I/O	• 32.768kHz crys	tal oscillator out	put				No
		 Pin functions 						
		General-purpos	e I/O					
		AD converter in	put port: AN11					
		Must be set for	oscillation and k	ept open if not	to be used.			
CF1	Input	Ceramic/crystal r	esonator input					No
CF2	Output	Ceramic/crystal r	esonator output					No

Port Output Types

The table below lists the types of port outputs and the presence/absence of a pull-up resistor. Data can be read into any input port even if it is in the output mode.

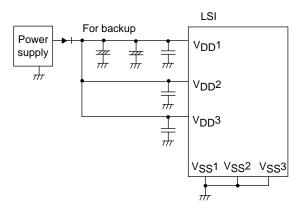
Port Name	Option selected in units of	Option type	Output type	Pull-up resistor
P00 to P07	1 bit	1	CMOS	Programmable (Note 1)
		2	Nch-open drain	No
P10 to P17	1 bit	1	CMOS	Programmable
P20 to P27 P30 to P34		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable
P71 to P73	-	No	CMOS	Programmable
PWM0, PWM1	-	No	CMOS	No
UHD+, UHD-	-	No	CMOS	No
XT1	-	No	Input only	No
XT2	-	No	32.768kHz crystal resonator output (N channel open drain when in general-purpose output mode)	No

Note 1: Programmable pull-up resistors for port 0 are controlled in 4 bit units (P00 to 03, P04 to 07).

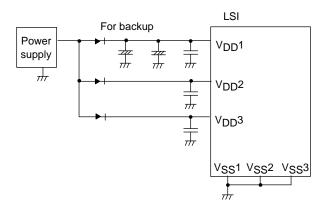
Power Pin Treatment

Connect the IC as shown below to minimize the noise input to the V_{DD1} pin. and extend the backup period. Be sure to electrically short the V_{SS1} , V_{SS2} , and V_{SS3} pins.

Example 1: When the microcontroller is in the backup state in the HOLD mode, the power to sustain the high level of output ports is supplied by their backup capacitors.



Example 2: The high level output at ports is not sustained and unstable in the HOLD backup mode.



USB Reference Power Option

When a voltage 4.5 to 5.5V is supplied to $V_{DD}1$ and the internal USB reference voltage circuit is activated, the reference voltage for USB port output is generated. The active/inactive state of the reference voltage circuit can be switched by option select. The procedure for marking the option selection is described below.

		(1)	(2)	(3)	(4)
Option settings	USB regulator	USE	USE	USE	NONUSE
	USB regulator at HOLD mode	USE	NONUSE	NONUSE	NONUSE
	USB regulator at HALT mode	USE	NONUSE	USE	NONUSE
Reference voltage circuit state	Normal mode	active	active	active	inactive
	HOLD mode	active	inactive	inactive	inactive
	HALT mode	active	inactive	active	inactive

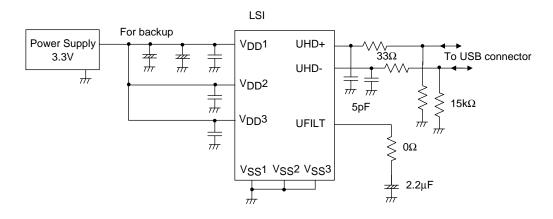
• When the USB reference voltage circuit is made inactive, the level of the reference voltage for USB port output is equal to V_{DD}1.

• Selection (2) or (3) can be used to set the reference voltage circuit inactive in HOLD or HALT mode.

• When the reference voltage circuit is activated, the current drain increases by approximately 100µA compared with when the reference voltage circuit is inactive.

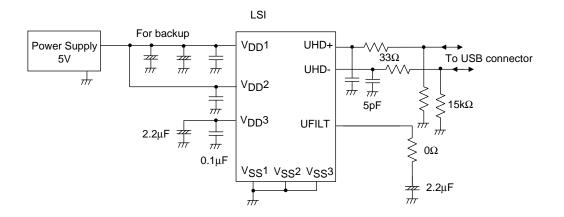
Example 1: VDD1=VDD2=3.3V

- Inactivating the reference voltage circuit (selection (4)).
- Connecting VDD3 to VDD1 and VDD2.



Example 2: VDD1=VDD2=5.0V

- Activating the reference voltage circuit (selection (1)).
- Isolating VDD3 from VDD1 and VDD2, and connecting capacitor between VDD3 and VSS.



Absolute Maximum Ratings at $Ta = 25^{\circ}C$,	$V_{SS1} = V_{SS2} = V_{SS3} = 0V$
--	------------------------------------

	Parameter	Symbol	Pin/Remarks	Conditions		1	Specif	ication	
	1 diamotor	-			V _{DD} [V]	min	typ	max	unit
Max	kimum supply voltage	V _{DD} max	V _{DD} 1, V _{DD} 2, V _{DD} 3	$V_{DD}1 = V_{DD}2 = V_{DD}3$		-0.3		+6.5	
Input voltage		V _I (1)	XT1, CF1			-0.3		V _{DD} +0.3	
	ut/output tage	V _{IO} (1)	Ports 0, 1, 2, 3, 7 PWM0, PWM1 XT2			-0.3		V _{DD} +0.3	V
	Peak output current	IOPH(1)	Ports 0, 1, 2	 When CMOS output type is selected Per 1 applicable pin 		-10			
		IOPH(2)	PWM0, PWM1	Per 1 applicable pin		-20			
rent		IOPH(3)	Port 3 P71 to P73	When CMOS output type is selected Per 1 applicable pin		-5			
	Average output current (Note 1-1)	IOMH(1)	Ports 0, 1, 2	When CMOS output type is selected Per 1 applicable pin		-7.5			
ıt cu		IOMH(2)	PWM0, PWM1	Per 1 applicable pin		-15			
High level output current		IOMH(3)	Port 3 P71 to P73	When CMOS output type is selected Per 1 applicable pin		-3			
	Total output current	ΣIOAH(1)	Ports 0, 2	Total current of all applicable pins		-25			
		ΣIOAH(2)	Port 1 PWM0, PWM1	Total current of all applicable pins		-25			
		ΣIOAH(3)	Ports 0, 1, 2 PWM0, PWM1	Total current of all applicable pins		-45			
		ΣIOAH(4)	Port 3 P71 to P73	Total current of all applicable pins		-10			
		ΣIOAH(5)	UHD+, UHD-	Total current of all applicable pins		-25			mA
	Peak output current	IOPL(1)	P02 to P07 Ports 1, 2 PWM0, PWM1	Per 1 applicable pin				20	
		IOPL(2)	P00, P01	Per 1 applicable pin				30	1
		IOPL(3)	Ports 3, 7 XT2	Per 1 applicable pin				10	
rrent	Average output current (Note 1-1)	IOML(1)	P02 to P07 Ports 1, 2 PWM0, PWM1	Per 1 applicable pin				15	
it cui		IOML(2)	P00, P01	Per 1 applicable pin				20	
Low level output current		IOML(3)	Ports 3, 7 XT2	Per 1 applicable pin				7.5	
-ow lev	Total output current	ΣIOAL(1)	Ports 0, 2	Total current of all applicable pins				45	
-		ΣIOAL(2)	Port 1 PWM0, PWM1	Total current of all applicable pins				45	
		ΣIOAL(3)	Ports 0, 1, 2 PWM0, PWM1	Total current of all applicable pins				80	
		ΣIOAL(4)	Ports 3, 7 XT2	Total current of all applicable pins				15	
		ΣIOAL(5)	UHD+, UHD-	Total current of all applicable pins				25	
	owable power sipation	Pd max	SQFP48(7×7)	Ta=-40 to +85°C				140	mV
	erating ambient mperature	Topr				-40		+85	°C
	orage ambient	Tstg				-55		+125	-U

Note 1-1: The average output current is an average of current values measured over 100ms intervals.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Allowable Operating Conditions at $Ta = -40^{\circ}C$ to $+85^{\circ}C$,	VSS1	$= V_{SS2} = V_{SS3} = 0V$
---	------	----------------------------

Parameter	Symbol	Pin/Remarks	Conditions			Specific	cation	<u> </u>
				V _{DD} [V]	min	typ	max	uni
Operating	V _{DD} (1)	V _{DD} 1=V _{DD} 2=V _{DD} 3	$0.245 \mu s \le tCYC \le 200 \mu s$		3.0		5.5	
supply voltage			$0.490 \mu s \le tCYC \le 200 \mu s$ Except		0.7		F F	
(Note 2-1)			in onboard programming mode		2.7		5.5	
Memory	VHD	V _{DD} 1=V _{DD} 2=V _{DD} 3	RAM and register contents					
sustaining			sustained in HOLD mode.		2.0		5.5	
supply voltage								
High level	V _{IH} (1)	Port 0, 1, 2, 3						
input voltage		P71 to P73			0.3V _{DD}			
		P70 port input/		2.7 to 5.5	+0.7		VDD	
		interrupt side						
	N/ (0)	PWM0, PWM1						-
	V _{IH} (2)	Port 70 watchdog		2.7 to 5.5	0.9V _{DD}		V _{DD}	
	V/(2)	timer side		071.55	0.751/			V
1	V _{IH} (3)	XT1, XT2, CF1, RES		2.7 to 5.5	0.75V _{DD}			
Low level	V _{IL} (1)	Port 1, 2, 3		4.0 to 5.5	VSS		0.1V _{DD}	
input voltage)/ (O)	P71 to P73					+0.4	
	V _{IL} (2)	P70 port input/ interrupt side		2.7 to 4.0	Vss		0.2V _{DD}	
	V _{IL} (3)	Port 0					0.15V _{DD}	
	VIL(0)	PWM0, PWM1		4.0 to 5.5	Vss		+0.4	
	V _{IL} (4)							
	. 17(.)			2.7 to 4.0	VSS		0.2V _{DD}	
	V _{IL} (5)	Port 70 watchdog					0.8V _{DD}	1
		timer side		2.7 to 5.5	VSS		-1.0	
	V _{IL} (6)	XT1, XT2, CF1, RES		2 7 to 5 5	Vee		0.25\/~~	
				2.7 to 5.5	V _{SS}		0.25V _{DD}	
Instruction	tCYC			3.0 to 5.5	0.245		200	
cycle time			Except for onboard programming	0.7 to 5.5	0.400		200	μs
(Note 2-2)			mode	2.7 to 5.5	0.490		200	
External	FEXCF(1)	CF1	• CF2 pin open					
system clock			System clock frequency					
frequency			division ratio=1/1	3.0 to 5.5	0.1		12	
			External system clock duty					
			=50±5%					мн
			CF2 pin open					
			System clock frequency	071.55				
			division ratio=1/1	2.7 to 5.5	0.1		6	
			 External system clock duty =50±5% 					
Oscillation	FmCF(1)	CF1, CF2	When 12MHz ceramic oscillation					
frequency			See Fig. 1.	3.0 to 5.5		12		
range	FmCF(2)	CF1, CF2	When 6MHz ceramic oscillation	<u> </u>			<u> </u>	мн
(Note 2-3)	1		See Fig. 1.	2.7 to 5.5		6		
	FmRC		Internal RC oscillation	2.7 to 5.5	0.3	1.0	2.0	1
	FsX'tal	XT1, XT2	32.768kHz crystal oscillation	2.7 10 0.0	0.0	1.0	2.0	
	1 37 101	AT1, AT2	See Fig. 2.	2.7 to 5.5		32.768		kH

Note 2-1: V_{DD} must be held greater than or equal to 3.0V in the flash ROM onboard programming mode.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Parameter	Symbol	Pin/Remarks	Conditions			Specifica	ation	
Falameter	Symbol	FIII/Remarks	Conditions	V _{DD} [V]	min	typ	max	uni
High level input current	I _{IH} (1)	Ports 0, 1, 2, 3 Port 7 RES PWM0, PWM1 UHD+, UHD-	Output disabled Pull-up resistor off VIN=VDD (Including output Tr's off leakage current)	2.7 to 5.5			1	
	I _{IH} (2)	XT1, XT2	Input port configuration VIN=VDD	2.7 to 5.5			1	
	I _{IH} (3)	CF1	V _{IN} =V _{DD}	2.7 to 5.5			15	
Low level input current	l _{IL} (1)	Ports 0, 1, 2, 3 Port 7 RES PWM0, PWM1 UHD+, UHD-	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	2.7 to 5.5	-1			μA
	I _{IL} (2)	XT1, XT2	Input port configuration	2.7 to 5.5	-1			
	I _{IL} (3)	CF1	V _{IN} =V _{SS}	2.7 to 5.5	-15			1
High level output	V _{OH} (1)	Ports 0, 1, 2, 3	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
voltage	V _{OH} (2)	P71 to P73	I _{OH} =-0.4mA	3.0 to 5.5	V _{DD} -0.4			1
	V _{OH} (3)		I _{OH} =-0.2mA	2.7 to 5.5	V _{DD} -0.4			
	V _{OH} (4)	PWM0, WM1	I _{OH} =-10mA	4.5 to 5.5	V _{DD} -1.5			1
	V _{OH} (5)	P05 to P07	I _{OH} =-1.6mA	3.0 to 5.5	V _{DD} -0.4			1
	V _{OH} (6)	(Note 3-1)	I _{OH} =-1mA	2.7 to 5.5	V _{DD} -0.4			1
Low level output	V _{OL} (1)	P00, P01	I _{OL} =30mA	4.5 to 5.5			1.5	
voltage	V _{OL} (2)		I _{OL} =5mA	3.0 to 5.5			0.4	V
	V _{OL} (3)		I _{OL} =2.5mA	2.7 to 5.5			0.4	
	V _{OL} (4)	Ports 0, 1, 2	I _{OL} =10mA	4.5 to 5.5			1.5	
	V _{OL} (5)	PWM0, PWM1	I _{OL} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (6)	XT2	I _{OL} =1mA	2.7 to 5.5			0.4	
	V _{OL} (7)	Ports 3, 7	I _{OL} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (8)		I _{OL} =1mA	2.7 to 5.5			0.4	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2, 3	V _{OH} =0.9V _{DD}	4.5 to 5.5	15	35	80	
	Rpu(2)	Port 7		2.7 to 5.5	18	50	150	kΩ
Hysteresis voltage	VHYS	RES Port 1, 2, 3, 7		2.7 to 5.5		0.1V _{DD}		v
Pin capacitance	СР	All pins	For pins other than that under test: VIN=VSS f=1MHz Ta=25°C	2.7 to 5.5		10		pF

Note 3-1: When the CKO system clock output function (P05) or audio interface output function (P05 to P07) is used.

Serial I/O Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

1. SIO0 Serial I/O Characteristics (Note 4-1-1)

ſ	Parameter	Symbol	Pin/	Conditions			Spec	ification	I
-			Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	Frequency	tSCK(1)	SCK0(P12)	See Fig. 8.		2			
	Low level pulse width	tSCKL(1)				1			
	High level pulse width	tSCKH(1)				1			
clock		tSCKHA(1a)	*	 Continuous data transfer mode USB, AIF, SIO4, SIO9, and DMCOPY not used at the same time. See Fig. 8. (Note 4-1-2) 		4			
Input clock		tSCKHA(1b)		 Continuous data transfer mode USB used at the same time. AIF, SIO4, SIO9, and DMCOPY not used at the same time. See Fig. 8. (Note 4-1-2) 	2.7 to 5.5	7			tCYC
5		tSCKHA(1c)		 Continuous data transfer mode USB, AIF, SIO4, SIO9, and DMCOPY used at the same time. See Fig. 8. (Note 4-1-2) 		9			
	Frequency	tSCK(2)	SCK0(P12)	When CMOS output type is selected		4/3			
8	Low level pulse width	tSCKL(2)		• See Fig. 8.			1/2		
	High level	tSCKH(2)					1/2		tSC⊭
ut clock	pulse width	tSCKHA(2a)		 Continuous data transfer mode USB, AIF, SIO4, SIO9, and DMCOPY not used at the same time. When CMOS output type is selected See Fig. 8. 		tSCKH(2) +2tCYC		tSCKH(2) + (10/3)tCYC	
Output		tSCKHA(2b)	•	 Continuous data transfer mode USB used at the same time. AIF, SIO4, SIO9, and DMCOPY not used at the same time. When CMOS output type is selected. See Fig. 8. 	2.7 to 5.5	tSCKH(2) +2tCYC		tSCKH(2) + (19/3)tCYC	tCYC
		tSCKHA(2c)		Continuous data transfer mode USB, AIF, SIO4, SIO9, and DMCOPY used at the same time When CMOS output type is selected See Fig. 8.		tSCKH(2) +2tCYC		tSCKH(2) + (25/3)tCYC	

Note 4-1-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.

Note 4-1-2: In an application where the serial clock input is to be used in the continuous data transfer mode, the time from SIORUN being set when serial clock is high to the falling edge of the first serial clock must be longer than tSCKHA.

Continued on next page.

		Parameter	Symbol	Pin/	Conditions			Spec	ification	
	Г	arameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
input	Da	ta setup time	tsDI(1)	SB0(P11), SI0(P11)	 Must be specified with respect to rising edge of SIOCLK. See Fig. 8. 		0.03			
Serial input	Da	ta hold time	thDI(1)			2.7 to 5.5	0.03			
	clock	Output delay time	tdD0(1)	SO0(P10), SB0(P11)	Continuous data transfer mode (Note 4-1-3)				(1/3)tCYC +0.05	μs
Serial output	Input clock		tdD0(2)		Synchronous 8-bit mode (Note 4-1-3)	2.7 to 5.5			1tCYC +0.05	
Seria	Output clock		tdD0(3)		(Note 4-1-3)				(1/3)tCYC +0.05	

Note 4-1-3: Must be specified with respect to falling edge of SIOCLK.

Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 8.

		D	Ourseland	Pin/	Quanditiona			Speci	fication	
		Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	ĸ	Frequency	tSCK(3)	SCK1(P15)	See Fig. 8.		2			
	Input clock	Low level pulse width	tSCKL(3)			2.7 to 5.5	1			
Serial clock	In	High level pulse width	tSCKH(3)				1			tCYC
Serial	ock	Frequency	tSCK(4)	SCK1(P15)	When CMOS output type is selected		2			
	Output clock	Low level pulse width	tSCKL(4)		• See Fig. 8.	2.7 to 5.5		1/2		10.014
	no	High level pulse width	tSCKH(4)					1/2		tSCK
Serial input	Da	ata setup time	tsDI(2)	SB1(P14), SI1(P14)	 Must be specified with respect to rising edge of SIOCLK. See Fig. 8. 	0.7.1.5.5	0.03			
Serial	Da	ata hold time	thDI(2)			2.7 to 5.5	0.03			
Serial output	Οι	itput delay time	tdD0(4)	SO1(P13), SB1(P14)	 Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 8. 	2.7 to 5.5			(1/3)tCYC +0.05	μs

2. SIO1 Serial I/O Characteristics (Note 4-2-1)

Note 4-2-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.

3. SIO4 Serial I/O Characteristics (Note 4-3-1)

Parameter	Symbol	Pin/	Conditions			Spec	ification	
alametei	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Frequency	tSCK(5)	SCK4(P24)	See Fig. 8.		2			
Low level	tSCKL(5)				1			
pulse width								
High level	tSCKH(5)				1			
pulse width	tSCKHA(5a)		 USB, SIO0 continuous transfer 					
			mode, AIF, SIO9, and DMCOPY					
					4			
			-					
				-				-
	tSCKHA(5b)							
				2.7 to 5.5				tCYC
					7			
			-					
	tSCKHA(5c)		USB, SIO0 continuous transfer					1
			mode, SIO9,					
			and DMCOPY used at the same					
			time.		12			
			AIF not used at the same time.					
			-					
Frequency								
		SCK4(P24)			4/3			
	tSCKL(6)					1/2		
			000 Hg. 0.					tSCk
-	13011(0)					1/2		
(Note 4-3-3)	tSCKHA(6a)		USB, SIO0 continuous transfer					
			mode, AIF, SIO9, and					
			DMCOPY not used at the same		tSCKH(6)		tSCKH(6)	
			time.		+		+	
			 When CMOS output type is 		(5/3)tCYC		(10/3)tCYC	
			-	-				-
	tSCKHA(6D)			2.7 to 5.5				
					tSCKH(6)		tSCKH(6)	
								tCYC
			selected.		· · /		· ,	
			• See Fig. 8.					
	tSCKHA(6c)		USB, SIO0 continuous transfer					
			mode, SIO9, and DMCOPY used					
			at the same time.		tSCKH(6)		tSCKH(6)	
		1	 AIF not used at the same time. 		+		+	
			When CMOS output type is selected.		(5/3)tCYC		(34/3)tCYC	
	Low level pulse width High level pulse width	Frequency tSCK(5) Low level tSCKL(5) pulse width tSCKH(5) pulse width tSCKH(5) pulse width tSCKHA(5a) pulse width tSCKHA(5a) frequency tSCKHA(5b) frequency tSCKHA(5c) Frequency tSCK(6) Low level tSCKL(6) pulse width tSCKHA(5a) High level tSCKL(6) pulse width tSCKHA(5a) (Note 4-3-3) tSCKHA(6a) itSCKHA(6b) tSCKHA(6b)	rameter Symbol Remarks Frequency tSCK(5) SCK4(P24) Low level tSCKL(5) pulse width tSCKH(5) pulse width tSCKHA(5a) ISCKHA(5a) ISCKHA(5b) tSCKHA(5b) Frequency tSCK(6) SCK4(P24) Low level tSCKL(6) pulse width tSCKH(6) pulse width tSCKH(6) pulse width tSCKHA(6a) High level tSCKHA(6a) KSCKHA(6b) tSCKHA(6b)	frequency tSCK(5) Remarks Conditions Frequency tSCK(5) SCK4(P24) See Fig. 8. Low level pulse width tSCKH(5) USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. • USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. tSCKHA(5a) tSCKHA(5b) • USB used at the same time. • See Fig. 8. tSCKHA(5c) tSCKHA(5c) • USB, SIO0 continuous transfer mode, AIF, SIO9, DMCOPY not used at the same time. • See Fig. 8. tSCKHA(5c) tSCKHA(5c) • USB, SIO0 continuous transfer mode, SIO9, and DMCOPY used at the same time. Frequency tSCK(6) SCK4(P24) • When CMOS output type is selected. pulse width (Note 4-3-3) tSCKH(6) SCK4(P24) • When CMOS output type is selected. pulse width (Note 4-3-3) tSCKHA(6a) • USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. tSCKHA(6b) tSCKHA(6b) • USB used at the same time. tSCK • USB used at the same time. tSCK • USB used at the same time. tSCKHA(6b) • USB used at the same time. tSCKHA(6b) • USB used at the same ti	arameter Symbol Remarks Conditions VppIVI Frequency tSCKI(5) SCK4(P24) See Fig. 8. See Fig. 8. See Fig. 8. High level tSCKH(5) tSCKH(5) USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. See Fig. 8. See Fig. 8. Stock 45.22) USB used at the same time. 2.7 to 5.5 tSCKHA(5b) tSCKHA(5c) USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. See Fig. 8. (Note 4-3-2) 2.7 to 5.5 tSCKHA(5c) tSCKHA(5c) USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. See Fig. 8. (Note 4-3-2) 2.7 to 5.5 Frequency tSCKH6(5c) tSCK4(P24) USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. See Fig. 8. (Note 4-3-2) Low level tSCKL(6) SCK4(P24) •USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. See Fig. 8. USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. pulse width tSCKH6(6b) tSCK4(F24) •USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. See Fig. 8. USB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same	arameter Symbol Remarks Conditions Vpp/V min Frequency tSCK4(5) SCK4(P24) See Fig. 8. 2 1 Low level pulse width tSCK4(5) SCK4(P24) See Fig. 8. 1 1 High level pulse width tSCKH4(5a) VSB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. 2.7 to 5.5 7 tSCKHA(5b) tSCKHA(5b) VSB, SIO0 continuous transfer mode, AIF, SIO9, DMCOPY not used at the same time. 2.7 to 5.5 7 tSCKHA(5b) tSCKHA(5b) VSB, SIO0 continuous transfer mode, AIF, SIO9, DMCOPY used at the same time. 2.7 to 5.5 7 tSCKHA(5b) tSCKHA(5b) VSB, SIO0 continuous transfer mode, SIO9, and DMCOPY used at the same time. 2.7 to 5.5 4/3 tow level tSCKH6(6) VMen CMOS output type is selected. 4/3 pulse width tSCKHA(6a) VBB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. 2.7 to 5.5 tSCKHA(6b) tSCKHA(6a) VBB, SIO0 continuous transfer mode, AIF, SIO9, and DMCOPY not used at the same time. 2.7 to 5.5 tSCKHA(6b) tSCKHA(6b) VBB, SIO0 c	arameter Symbol Remarks Conditions VpplVI min vpp Frequency tSCK4(5) SCK4(P24) See Fig. 8. 2 1 Jules width tSCKH(5) SCK4(P24) See Fig. 8. 1 1 Jules width tSCKH(5) tSCK4(F24) See Fig. 8. 1 1 Jules width tSCKH(5) tSCK4(F24) See Fig. 8. 1 1 1 USB stod at the same time. See Fig. 8. (Note 4-3-2) 1 2.7 to 5.5 7 tSCKHA(5c) tSCKHA(5c) USB stod continuous transfer mode, AF, SIO9, MCOPY not used at the same time. See Fig. 8. 1 1 tSCKHA(5c) tSCK4(F24) Vules SiO0 continuous transfer mode, SIO9, and DMCOPY used at the same time. 12 12 Frequency tSCK4(6) Vibe Not CMOS output type is selected. See Fig. 8. 4/3 12 Low level tSCKHA(6b) tSCKHA(6b) Vibe CMOS output type is selected. See Fig. 8. 1/2 1/2 Jules width tSCKHA(6b) Vibe CMOS output type is selec	arameter Symbol Remarks Conditions Vpp[V] min typ max Frequency ISCK(5) SCK4(P24) See Fig. 8. 2 1

Note 4-3-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.

Note 4-3-2: In an application where the serial clock input is to be used in the continuous data transfer mode, the period from the time SI4RUN is set with the serial clock set high to the falling edge of the first serial clock must be longer than tSCKHA.

Note 4-3-3: When using the serial clock output, make sure that the load at the SCK4 (P24) pin meets the following conditions:

Clock rise time tSCKR < 0.037µs (see Figure 12.) at Ta=+25°C, VDD=3.3V

Continued on next page.

	tinued from preceding		Pin/			ification	cation		
	Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
input	Data setup time	tsDI(3)	SO4(P22), SI4(P23)	 Must be specified with respect to falling edge of SIOCLK. See Fig. 8 		0.03			
Serial	Data hold time	thDI(3)	-		2.7 to 5.5	0.03			
Serial output	Output delay time	tdD0(5)	SO4(P22), SI4(P23)	 Must be specified with respect to rising edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 8. 	2.7 to 5.5			(1/3)tCYC +0.05	μs

4. SIO9 Serial I/O Characteristics (Note 4-4-1)

	-	Parameter	Cumbol	Pin/	Conditions			Specifi	cation	
	P	rarameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(7)	SCK9(P27)	See Fig. 8.		2			
		Low level pulse width	tSCKL(7)				1			
		High level pulse width	tSCKH(7)				1			
lock	ock		tSCKHA(7a)		 USB, SIO0 continuous transfer mode, AIF, SIO4 and DMCOPY not used at the same time. See Fig. 8. (Note 4-4-2) 		4			
Serial clock	Input clock		tSCKHA(7b)		 USB used at the same time. SIO0 continuous transfer mode, AIF, SIO4, and DMCOPY not used at the same time. See Fig. 8. (Note 4-4-2) 	2.7 to 5.5	7			tCYC
			tSCKHA(7c)		 USB, SIO0 continuous transfer mode, SIO4 and DMCOPY used at the same time. AIF not used at the same time. See Fig. 8. (Note 4-4-2) 		15			

Note 4-4-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.

Note 4-4-2: In an application where the serial clock input is to be used in the continuous data transfer mode, the period from the time SI9RUN is set with the serial clock set high to the falling edge of the first serial clock must be longer than tSCKHA.

Continued on next page

Con	ntinue	ed from precedin	g page	1	1					
	F	Parameter	Symbol	Pin/	Conditions			•	fication	
		Frequency	tSCK(8)	Remarks SCK9(P27)	When CMOS output type is selected.	V _{DD} [V]	min 4/3	typ	max	unit tCYC
		Low level pulse width	tSCKL(8)		• See Fig. 8.			1/2	I	40.01/
		High level pulse width	tSCKH(8)					1/2		tSCK
S	Ş	(Note 4-4-3)	tSCKHA(8a)		 USB, SIO0 continuous transfer mode, AIF SIO4 DMCOPY not used at the same time. When CMOS output type is selected. See Fig. 8. 		tSCKH(8) + (5/3)tCYC		tSCKH(8) + (10/3)tCYC	
Serial clock	Output clock		tSCKHA(8b)		 USB used at the same time. SIO0 continuous transfer mode, AIF, SIO4, and DMCOPY not used at the same time. When CMOS output type is selected See Fig. 8. 	2.7 to 5.5	tSCKH(8) + (5/3)tCYC		tSCKH(8) + (19/3)tCYC	tCYC
			tSCKHA(8c)		 USB, SIO0 continuous transfer mode, SIO4, and DMCOPY used at the same time. AIF not used at the same time. When CMOS output type is selected. See Fig. 8. 		tSCKH(8) + (5/3)tCYC		tSCKH(8) + (43/3)tCYC	
input		ta setup time	tsDI(4)	SO9(P25), SI9(P26)	Must be specified with respect to rising edge of SIOCLK. See Fig. 8.		0.03			
Serial input	Da	ta hold time	thDI(4)			2.7 to 5.5	0.03			
Serial output	Οι	itput delay time	tdDO(6)	SO9(P25), SI9(P26)	 Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode See Fig. 8. 	2.7 to 5.5			(1/3)tCYC +0.05	μs

Note 4-4-3: When using the serial clock output, make sure that the load at the SCK9 (P27) pin meets the following conditions:

Clock rise time tSCKR $< 0.037 \mu s$ (see Figure 12.) at Ta=+25°C, VDD=3.3V

Pulse Input Conditions at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Decemeter	Cumhal	Pin/Remarks	Conditions			Speci	fication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High/low level pulse width	tP1H(1) tP1L(1)	INT0(P70), INT1(P71), INT2(P72), INT4(P20 to P23), INT5(P24 to P27), INT6(P20), INT7(P24)	 Interrupt source flag can be set. Event inputs for timer 0 or 1 are enabled. 	2.7 to 5.5	1			
	tPIH(2) tPIL(2)	INT3(P73) when noise filter time constant is 1/1	 Interrupt source flag can be set. Event inputs for timer 0 are enabled. 	2.7 to 5.5	2			tCYC
	tPIH(3) tPIL(3)	INT3(P73) when noise filter time constant is 1/32	 Interrupt source flag can be set. Event inputs for timer 0 are nabled. 	2.7 to 5.5	64			
	tPIH(4) tPIL(4)	INT3(P73) when noise filter time constant is 1/128	 Interrupt source flag can be set. Event inputs for timer 0 are enabled. 	2.7 to 5.5	256			
	tPIL(5)	RMIN(P73)	Recognized by the infrared remote control receiver circuit as a signal	2.7 to 5.5	4			RMCK (Note 5-1)
	tPIL(6)	RES	Resetting is enabled.	2.7 to 5.5	200			μs

Note 5-1: Represents the period of the reference clock (1 tCYC to 128 tCYC or the source frequency of the subclock) for the infrared remote control receiver circuit.

AD Converter Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, VSS1 =	$= V_{SS}2 = V_{SS}3 = 0V$
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				Specification				
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN0(P00) to		3.0 to 5.5		8		bit
Absolute accuracy	ET	AN7(P07), AN8(P70),	(Note 6-1)	3.0 to 5.5			±1.5	LSB
Conversion time	TCAD	AN9(P71),	AD conversion time=32×tCYC		15.68		97.92	
		AN10(XT1), AN11(XT2)	(when ADCR2=0) (Note 6-2)	4.5 to 5.5	(tCYC=		(tCYC=	
					0.490µs)		3.06µs)	
					23.52		97.92	
				3.0 to 5.5	(tCYC=		(tCYC=	
					0.735µs)		3.06µs)	
			AD conversion time=64×tCYC		18.82		97.92	μs
			(when ADCR2=1) (Note 6-2)	4.5 to 5.5	(tCYC=		(tCYC=	
					0. 294µs)		1.53µs)	
					47.04		97.92	
				3.0 to 5.5	(tCYC=		(tCYC=	
					0.735µs)		1.53µs)	
Analog input voltage range	VAIN			3.0 to 5.5	V _{SS}		V _{DD}	V
Analog port input current	IAINH		VAIN=V _{DD}	3.0 to 5.5			1	
	IAINL	1	VAIN=V _{SS}	3.0 to 5.5	-1			μA

Note 6-1: The quantization error ($\pm 1/2$ LSB) is excluded from the absolute accuracy.

Note 6-2: The conversion time refers to the period from the time when an instruction for starting a conversion process is issued to the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

Consumption Current Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Parameter	Symbol	Pin/	Conditions		Specification				
	-	Remarks		V _{DD} [V]	min	typ	max	unit	
Normal mode consumption current (Note 7-1)	IDDOP(1)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	 FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side Internal PLL oscillation stopped 	4.5 to 5.5		9.8	24		
	IDDOP(2)		Internal RC oscillation stopped USB circuit stopped 1/1 frequency division ratio	3.0 to 3.6		5.7	14		
	IDDOP(3)		FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		15	35		
	IDDOP(4)		 Internal PLL oscillation mode active Internal RC oscillation stopped USB circuit active 1/1 frequency division ratio 	3.0 to 3.6		7.7	20	mA	
	IDDOP(5)		• FmCF=12MHz ceramic oscillation mode	4.5 to 5.5		6.7	16		
	IDDOP(6)		 FsX'tal=32.768kHz crystal oscillation mode System clock set to 6MHz side 	3.0 to 3.6		3.9	9.0		
	IDDOP(7)		 Internal RC oscillation stopped 1/2 frequency division ratio 	2.7 to 3.0		3.2	7.3		
	IDDOP(8)		 FmCF=0Hz(oscillation stopped) 	4.5 to 5.5	0.72	3.4			
	IDDOP(9)		 FsX'tal=32.768kHz crystal oscillation mode System clock set to internal RC oscillation. 	3.0 to 3.6		0.41	1.9		
	IDDOP(10)		• 1/2 frequency division ratio	2.7 to 3.0		0.35	1.5		
	IDDOP(11)		 FmCF=0Hz(oscillation stopped) FsX'tal=32.768kHz crystal oscillation mode 	4.5 to 5.5		45	184		
	IDDOP(12)		 System clock set to crystal oscillation. (32.768kHz) 	3.0 to 3.6		18	65	μΑ	
	IDDOP(13)		 Internal RC oscillation stopped 1/2 frequency division ratio 	2.7 to 3.0		14	47		
HALT mode consumption current (Note7-1)	IDDHALT(1)		 HALT mode FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side 	4.5 to 5.5		4.9	12		
	IDDHALT(2)		 Internal PLL oscillation stopped Internal RC oscillation stopped USB circuit stopped 1/1 frequency division ratio 	3.0 to 3.6		2.7	6.4		
	IDDHALT(3)		HALT mode FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		9.5	23		
	IDDHALT(4)		 Internal PLL oscillation mode active Internal RC oscillation stopped USB circuit active 1/1 frequency division ratio 	3.0 to 3.6		4.7	12	mA	
	IDDHALT(5)		HALT mode FmCF=12MHz ceramic oscillation mode	4.5 to 5.5		3.0	7.3		
	IDDHALT(6)		 FsX'tal=32.768kHz crystal oscillation mode System clock set to 6MHz side 	3.0 to 3.6		1.6	3.8		
	IDDHALT(7)		 Internal RC oscillation stopped 1/2 frequency division ratio 	2.7 to 3.0		1.3	2.9		
	IDDHALT(8)	-	HALT mode FmCF=0Hz(oscillation stopped)	4.5 to 5.5		0.41	2.0		
	IDDHALT(9)		FsX'tal=32.768kHz crystal oscillation mode	3.0 to 3.6		0.20	0.95	l	
		OHALT(10) System clock set to internal RC oscillation 1/2 frequency division ratio			_	0.17	0.70		

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

Continued on next page.

Parameter	Symbol	Pin/	Conditions		Specification				
	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
HALT mode consumption	IDDHALT(11)	V _{DD} 1 =V _{DD} 2	HALT mode FmCF=0MHz (oscillation stopped)	4.5 to 5.5		31	132		
current (Note 7-1)	IDDHALT(12)	=V _{DD} 3	 • FsX'tal=32.768kHz crystal oscillation mode • System clock set to crystal oscillation. 			9.1	39		
	IDDHALT(13)		 (32.768kHz) Internal RC oscillation stopped 1/2 frequency division ratio 	2.7 to 3.0		6.3	27		
HOLD mode	IDDHOLD(1)	V _{DD} 1	HOLD mode	4.5 to 5.5		0.14	39	μΑ	
consumption	IDDHOLD(2)		 CF1=V_{DD} or open (External clock mode) 	3.0 to 3.6		0.04	19		
current	IDDHOLD(3)			2.7 to 3.0		0.04	17		
Timer HOLD mode consumption current	IDDHOLD(4)		Timer HOLD mode	4.5 to 5.5		25	115		
	IDDHOLD(5)	1	 CF1=V_{DD} or open (External clock mode) 	3.0 to 3.6		6.0	32		
	IDDHOLD(6)]	 FsX'tal=32.768kHz crystal oscillation mode 	2.7 to 3.0		3.7	20		

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors

USB Characteristics and Timing at $Ta=-40^{\circ}C$ to $+85^{\circ}C,\,V_{SS}1=V_{SS}2=V_{SS}3=0V$

Deservator	Querra had	Quanditiana	Specifi	Specification			
Parameter	Symbol	Conditions	min	typ	max	unit	
High level output	VOH(USB)	• 15kΩ±5% to GND	2.8		3.6	V	
Low level output	VOL(USB)	• 1.5kΩ±5% to 3.6V	0.0		0.3	V	
Output signal crossover voltage	VCRS		1.3		2.0	V	
Differential input sensitivity	V _{DI}	• (UHD+)-(UHD-)	0.2			V	
Differential input common mode range	V _{CM}		0.8		2.5	V	
High level input	VIH(USB)		2.0			V	
Low level input	VIL(USB)				0.8	V	
USB data rise time	^t R	• R _S =33Ω, C _L =50pF	4		20	ns	
USB data fall time	^t F	• R _S =33Ω, C _L =50pF	4		20	ns	

F-ROM Programming Characteristics at $Ta = +10^{\circ}C$ to $+55^{\circ}C$, $V_{SS}1 = 0V$

Deservation	Quarter al	Pin/			Specification			
Parameter	Symbol	Remarks	Conditions		min	typ	max	unit
Onboard programming current	IDDFW(1)	V _{DD} 1	 Excluding power dissipation in the microcontroller block 	3.0 to 5.5		5	10	mA
Programming time	tFW(1)		Erase operation	0.01.55		20	30	ms
	tFW(2) • Write o		Write operation	3.0 to 5.5		40	60	μs

Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 shows the characteristics of a oscillation circuit when USB host function is not used.

If USB host function is to be used, it is absolutely recommended to use an oscillator that satisfies the precision and stability according to the USB standards.

Nominal Vendor Frequency Name	Vendor		Circuit Constant			Oscillation Stabilization Time			
	Name Oscillator Name	C1 [pF]	C2 [pF]	Rd1 [Ω]	Range [V]	typ [ms]	max [ms]	Remarks	
6MHz	MURATA	CSTCR6M00GH5L**-R0	(39)	(39)	1k	2.7 to 5.5	0.1	0.5	
8MHz	MURATA	CSTCE8M00GH5L**-R0	(33)	(33)	470	3.0 to 5.5	0.1	0.5	C1 and C2
10MHz	MURATA	CSTCE10M0GH5L**-R0	(33)	(33)	330	3.0 to 5.5	0.1	0.5	integrated
12MHz	MURATA	CSTCE12M0GH5L**-R0	(33)	(33)	330	3.0 to 5.5	0.1	0.5	SMD type

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized in the following cases (see Figure 4):

- Till the oscillation gets stabilized after VDD goes above the operating voltage lower limit.
- Till the oscillation gets stabilized after the instruction for starting the main clock oscillation circuit is executed
- Till the oscillation gets stabilized after the HOLD mode is reset.
- Till the oscillation gets stabilized after the X'tal HOLD mode is reset with CFSTOP (OCR register, bit 0) set to 0

Characteristics of a Sample Subsystem Clock Oscillator Circuit

Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 2 Cha	Table 2 Characteristics of a Sample Subsystem Clock Oscinator Circuit with a Crystal Oscinator										
Nominal	Vendor	Vendor		Circuit Constant				ing Oscillation ge Stabilization Time		Demerius	
Frequency	Frequency Name	Oscillator Name	C3 [pF]	C4 [pF]	Rf [Ω]	Rd2 [Ω]	Range [V]	typ [s]	max [s]	Remarks	
32.768kHz	EPSON TOYOCOM	MC-306	18	18	OPEN	560k	2.7 to 5.5	1.1	3.0	Applicable CL value=12.5pF	

Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit with a Crystal Oscillator

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized in the following cases (see Figure 4):

- Till the oscillation gets stabilized after the instruction for starting the subclock oscillation circuit is executed
- Till the oscillation gets stabilized after the HOLD mode is reset with EXTOSC (OCR register, bit 6) set to 1
- Note: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.

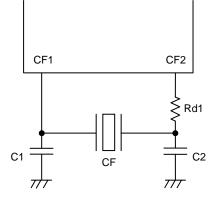


Figure 1 CF Oscillator Circuit

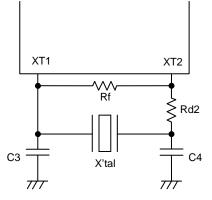
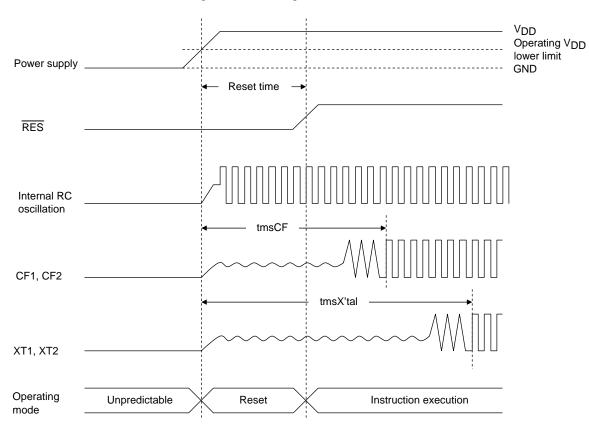


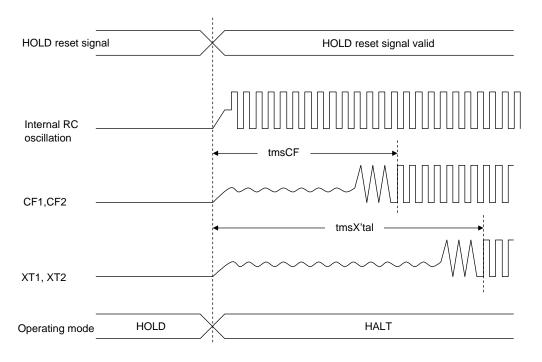
Figure 2 Crystal Oscillator Circuit



Figure 3 AC Timing Measurement Point

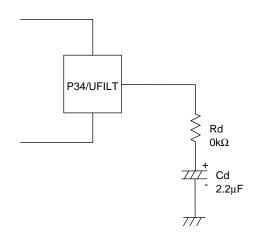


Reset Time and Oscillation Stabilization Time

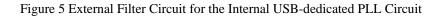


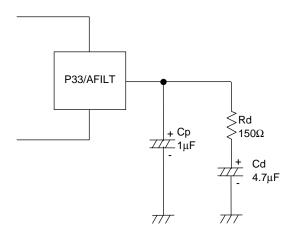
HOLD Reset Signal and Oscillation Stabilization Time

Figure 4 Oscillation Stabilization Time

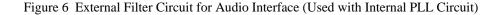


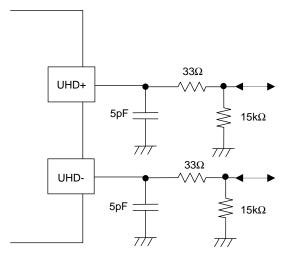
When using the internal PLL circuit to generate the 48MHz clock for USB, it is necessary to connect a filter circuit such to the P34/UFILT pin such as that shown in the left Fig.





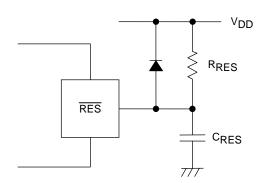
To generate the master clock for the audio interface using the internal PLL circuit, it is necessary to connect a filter circuit to the P33/AFILT pin that is shown in the left Fig.





It's necessary to adjust the Circuit Constant of the USB Port Peripheral Circuit for each mounting board.





Note:

Determine the value of C_{RES} and R_{RES} so that the reset signal is present for a period of 200µs after the supply voltage goes beyond the lower limit of the IC's operating voltage.



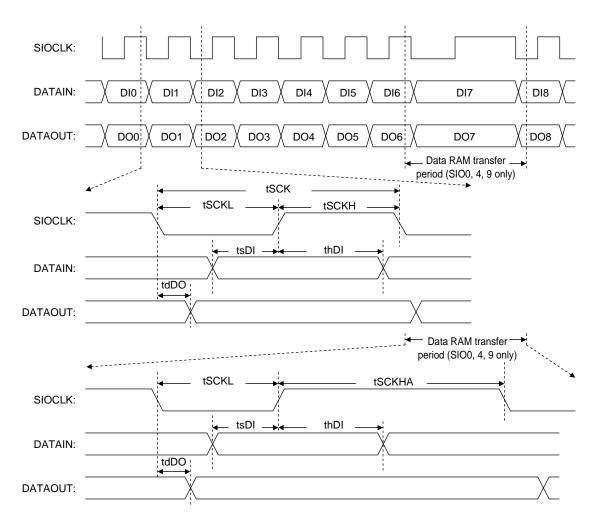
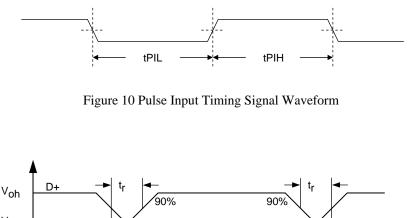


Figure 9 Serial Input/Output Waveform



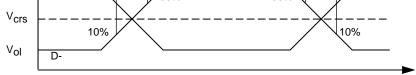
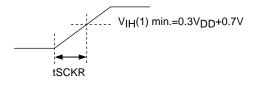
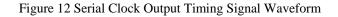


Figure 11 USB Data Signal Timing and Voltage Level



tSCKR:

Defined as the time period from the time the state of the output starts changing till the time it reaches the minimum value of $V_{IH}(1)$.



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